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JC904 U.S. PTO

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TRANSMITTAL FORM

I hereby certify that this correspondence is being deposited with the United States Postal Service as "Express Mail" under Label No. EL 886 594 314 US in an envelope addressed to: Box Patent Application, Assistant Commissioner for Patents, Washington, D.C. 20231 on:

January 14, 2002
(Date of Deposit)

Kathy Dixon
Kathy Dixon

11011 U.S. PTO
10/047266
01/14/02

Box Patent Application
Assistant Commissioner
For Patents
Washington, D.C. 20231

Attorney Doc. #: 67,200-641
Mailing Date: Jan. 14, 2002

Dear Sir:

Transmitted herewith for filing is the patent application of:

Inventor(s): Chih-Ming Ke Tsai-Sheng Gau
Jaw-Jung Shin Anthony Yen

For: Reducing Photoresist Shrinkage Via Plasma Treatment

Submitted herewith are:

- X 3 sheets of formal drawings showing Figs 1-4
- X An Assignment of the invention to Taiwan Semiconductor Manufacturing Co., Ltd., together with Assignment Recordal Sheet
- X A Declaration for patent application under CFR 1.63 and 1.68

The filing fee has been calculated as shown below:

	No. Filed	No. Extra	Small Entity Fee	Large Entity Fee	Total
Basic Fee			\$370.00	\$740.00	\$740.00
Total Claims	20x20	0 x	\$9.00	\$18.00	\$0
Indep. Claims	3 -3	0 x	\$42.00	\$84.00	\$0
Multiple Dep. Clms.			\$140.00	\$280.00	\$0
Assign. Rec. Fee			\$40.00	\$40.00	\$40.00
TOTAL					\$780.00